

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsien-Cheng WANG	05/08/2006
Chin-Hsiang LIN	05/15/2006
H. J. LEE	05/12/2006
Ching-Yu CHANG	05/09/2006
Hua-Tai LIN	05/09/2006
Burn Jeng LIN	05/17/2006

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Road 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11462413

CORRESPONDENCE DATA

Fax Number: (214)200-0853
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 214-651-5000
Email: bonnie.boyle@haynesboone.com
Correspondent Name: Haynes and Boone, LLP
Address Line 1: 901 Main Street, Suite 3100
Address Line 4: Dallas, TEXAS 75202

ATTORNEY DOCKET NUMBER: 24061.698

PATENT

REEL: 018054 FRAME: 0293

500134668

CH \$40.00 11462413

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

source=698Assignment#page1.tif

source=698Assignment#page2.tif

source=698Assignment#page3.tif

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Hsien-Cheng WANG | of | 10F, 24, Lane 23, Chien-Chung Road 1
Hsinchu, 300 Taiwan, R.O.C. |
| (2) | Chin-Hsiang LIN | of | No. 37, Lane 393, Min-hu Road
Hsin-Chu 300, Taiwan, R.O.C. |
| (3) | H. J. Lee | of | No. 8, Li-Hsin Road 6
Hsin-Chu 300, Taiwan, R.O.C. |
| (4) | Ching-Yu CHANG | of | No. 17, Hsinchen Road, Yilang Village
Yilang County 264, Taiwan, R.O.C. |
| (5) | Hua-Tai LIN | of | 3F, No. 2-6, Bamboo Road
Hsin-Chu 300, Taiwan, R.O.C. |
| (6) | Burn Jeng LIN | of | 153 Guang Fu Road, Sec. 1, Lane 89, 1 st FL
Hsin-Chu 300, Taiwan, R.O.C. |

have invented certain improvements in

**NOVEL PHOTORESIST MATERIALS AND
PHOTOLITHOGRAPHY PROCESS**

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on August 4, 2006 and assigned application number 11/462,413; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all

Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsien-Cheng WANG

Residence Address: 10F, 24, Lane 23, Chien-Chung Road 1
Hsinchu, 300 Taiwan, R.O.C.

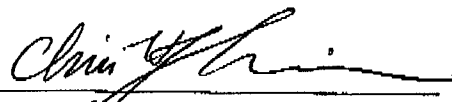
Dated: 08, May, 2006


Inventor Signature

Inventor Name: Chin-Hsiang LIN

Residence Address: No. 37, Lane 393, Min-hu Road
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 5/15/2006


Inventor Signature

Inventor Name: H. J. LEE

Residence Address: No. 8, Li-Hsin Road 6
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 5.12.2006

HJ Lee
Inventor Signature

Inventor Name: Ching-Yu CHANG

Residence Address: No. 17, Hsinchen Road, Yuansun Village
Yuansun County 264, Taiwan, R.O.C.

Dated: 5-9.2006

張育昌
Inventor Signature

Inventor Name: Hua-Tai LIN

Residence Address: 3F, No. 2-6, Bamboo Road
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 05/09/2006

Hua Tai Lin
Inventor Signature

Inventor Name: Burn Jeng LIN

Residence Address: 153, Guang Fu Road, Sec. 1, Lane 89, 1st Fl.
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 5/17/2006

Burn Jeng Lin
Inventor Signature